

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 10/014,310
Filing Date December 11, 2001
Inventor Ritesh P. Shah, et al.
Assignee Honeywell International Inc.
Group Art Unit 1753
Examiner A. Oltmans
Attorney's Docket No. 32120-CON1
Title: Methods of Forming Metal Articles

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

References -See Attached Form PTO-1449

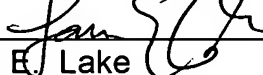
The Examiner's attention is directed to the references which are listed on the attached Form PTO-1449, copies of which are attached. No admission is made regarding whether all the submitted references are prior art.

Citation of the referenced art is respectfully requested.

Respectfully submitted,

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Dated: 01 Dec 2003

By: 
James E. Lake
Reg. No. 44,854

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Form PTO-1400		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. 32120-CON1		SERIAL NO. 10/014,310	
LIST OF PART CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT Ritesh P. Shah, et al.			
				FILING DATE December 11, 2001		GROUP 1753	
U.S. PATENT DOCUMENTS							
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA	4,844,746	07/1989	Hormann et al			
	AB	6,521,173	02/2003	Kumar			
	AC	6,454,994	09/2002	Wang			
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
	AL						
FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Country	Class	Subclass	Translation
							Yes No
	AM	JP-H03-197640A	08/1991	Japan			
	AN	EP 0902102 A1	08/1998	EPO			
	AO	EP 0281141 B2	03/1988	EPO			
	AP	JP59227992A	12/1984	Japan			
	AO						
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
	AR		"Nickel, Cobalt and Their Alloys", pub. By ASM International, December 2000, pages 76, 230-234.				
	AS		S. Sawada, "On Advanced Sputtering Targets of Refractory Metals and Their Silicides for VLSI-Applications", 12 th International Plansee Seminar, 1989, Top 5: Ultrapure Refractory Metals, pgs. 207, 216.				
	AT		P. Ding et al, "Copper Barrier, Seed Layer, and Planarization Technologies", June 10-12, 1997 VMIC Conference 1997, ISMIC-107/97/0087(c), pgs. 87-92.				
EXAMINER				DATE CONSIDERED			
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							

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